

BOARD CHARACTERISTICS

Copper Layer Count: 4

Board Thickness: 0.8000 mm

Board overall dimensions: 22.0000 mm x 22.0000 mm

Min track/spacing: 0.1016 mm / 0.1016 mm

Min hole diameter: 0.2000 mm

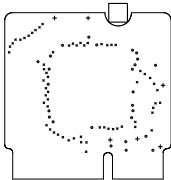
Copper Finish: ENIG

Impedance Control: No

Castellated pads: No

Plated Board Edge: No

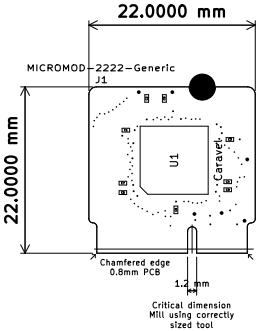
Edge card connectors: Yes, Bevelled



Drill Map:

- 0.203mm / 0.0080" (63 holes)
- 0.250mm / 0.0098" (26 holes)
- 0.500mm / 0.0197" (6 holes)
- 3.500mm / 0.1378" (1 hole)

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
GND	copper		0.035 mm		1	0
Dielectric	core	FR4	0.44 mm	Not specified	4.5	0.02
PWR	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



45 degree chamfered edge
0.8mm PCB
4-layer Design
Efabless

Sheet:
File: caravel-M.2-card-QFN.kicad_pcb

Title: Carvel Breakout board as M.2 Card

Size: A4	Date:	Rev: 1
KiCad E.D.A. kicad 7.0.7-7.0.7-ubuntu22.04.1		Id: 1/1